



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-06-28
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L9300TU80T-TR	A0UX*UAL3BFP	A	0959	2017-06-28
Amount	UoM	Unit type	ST ECOPACK Grade	
520.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	NiPdAuAg	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	14-14-1	80	gull wing	
Comment	TQFP 80L 14X14X1.0 EXPAD UP			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			TRUE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			FALSE
Substance	amount in product (mg)	Application	ppm in product
Nickel	6.73	side metal- Leadframe metal- Leadfra	12937
Cobalt	0.002	Die metal	4

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	AOLUX*UAL3BFP									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or Dies (choose)	Other inorganic materials	22.526	mg	supplier	die	Silicon (Si)	7440-21-3		20.394	mg	905354	39219				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.048	mg	2131	92				
				supplier	metallization	Copper (Cu)	7440-50-8		1.263	mg	56069	2429				
				supplier	metallization	Cobalt (Co)	7440-48-4		0.002	mg	89	4				
				supplier	metallization	Platinum (Pt)	7440-06-4		0.087	mg	3862	167				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	355	15				
				supplier	metallization	Tungsten (W)	7440-33-7		0.072	mg	3196	138				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.313	mg	13895	602				
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.012	mg	533	23				
				supplier	back side metallization	Gold (Au)	7440-57-5		0.031	mg	1376	60				
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.058	mg	2575	112				
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.003	mg	133	6				
				supplier	polymer die coating	Polyimide AH 1200	Proprietary		0.235	mg	10432	452				
				Leadframe	Copper & its alloys	191.304	mg	supplier	alloy	Copper (Cu)	7440-50-8		183.024	mg	956718	351969
								supplier	alloy	Nickel (Ni)	7440-02-0		5.708	mg	29837	10977
supplier	alloy	Magnesium (Mg)	7439-95-4						0.285	mg	1490	548				
supplier	alloy	Silicon (Si)	7440-21-3						1.237	mg	6466	2379				
supplier	metallization	Nickel (Ni)	7440-02-0						0.961	mg	5023	1848				
supplier	metallization	Palladium (Pd)	7440-05-3						0.031	mg	162	60				
supplier	metallization	Gold (Au)	7440-57-5						0.029	mg	152	56				
supplier	metallization	Silver (Ag)	7440-22-4						0.029	mg	152	56				
Die attach	Other Organic Materials	5.257	mg	supplier	glue or tape (choose)	Silver (Ag)	7440-22-4		4.705	mg	894997	9048				
				supplier	glue or tape	Isobornyl Methacrylate	7534-94-3		0.394	mg	74948	758				
				supplier	glue or tape	Bismaleimide resin	Proprietary		0.158	mg	30055	304				
Bonding wires	Other inorganic materials	3.914	mg	supplier	wire	Copper (Cu)	7440-50-8		3.914	mg	1000000	7527				
Encapsulation	Other Organic Materials	296.999	mg	supplier	mold compound	Silica, vitreous	60676-86-0		256.607	mg	864000	493475				
				supplier	mold compound	Epoxy Resin	25068-38-6		22.275	mg	75000	42837				
				supplier	mold compound	Phenol Resin	29690-82-2		14.850	mg	50000	28557				
				supplier	mold compound	3-Mercaptopropyl trimethoxysilane	4420-74-0		1.485	mg	5000	2856				
				supplier	mold compound	Quartz	14808-60-7		0.891	mg	3000	1713				
supplier	mold compound	Carbon black	1333-86-4		0.891	mg	3000	1713								